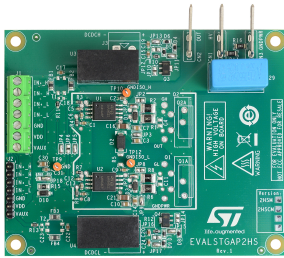


## Demonstration board for STGAP2HSCM isolated 4 A single gate driver



### Features

- **Board**
  - High voltage rail up to 1200 V
  - Negative gate driving
  - Onboard isolated DC-DC converters to supply high-side and low-side gate drivers, fed by VAUX = 5 V, with 5.2 kV maximum isolation
  - 3.3 V VDD logic supply generated onboard or 5 V (externally applied)
  - Easy jumper selection of driving voltage configuration: +15/0 V; +15/-3 V; +19/0 V; +19/-3 V;
- **Device**
  - Driver current capability: 4 A source/sink @ 25°C
  - 6000 V Galvanic isolation
  - Short propagation delay: 75 ns
  - UVLO function
  - Gate driving voltage up to 26 V
  - 3.3 V, 5 V TTL/CMOS inputs with hysteresis
  - Temperature shutdown protection
  - Standby function
  - 4 A Miller CLAMP

### Description

The EVALSTGAP2HSCM is an isolated single gate driver.

The gate driver is characterized by 4 A current capability and rail-to-rail outputs, making the device suitable also for high power inverter applications such as motor drivers in industrial applications equipped with MOSFET / IGBT power switch.

The configuration featuring single output pin and Miller CLAMP function allows avoiding gate spikes during fast commutations in half-bridge topologies.

The device integrates protection functions: UVLO and thermal shutdown are included to easily design high reliability systems. Dual input pins allow choosing the control signal polarity and also implementing HW interlocking protection in order to avoid cross-conduction in case of controller's malfunction.

The device allows implementing negative gate driving, and the onboard isolated DC-DC converters allow working with optimized driving voltage for MOSFET/IGBT.

The EVALSTGAP2HSCM board allows evaluating all the STGAP2HSCM features while driving a half-bridge power stage with voltage rating up to 1200 V in TO-220 or TO-247 package.

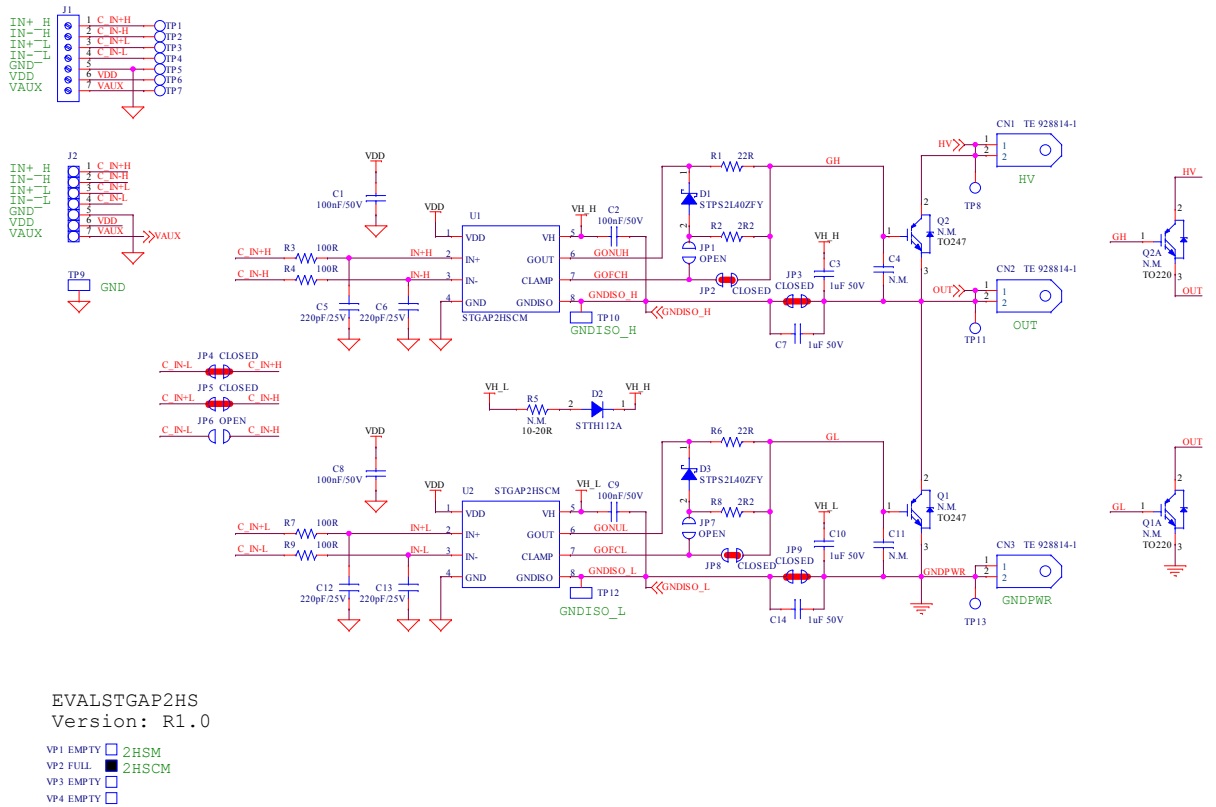
The board allows easily selecting and modifying the values of relevant external components in order to ease driver performance evaluation under different applicative conditions and fine pre-tuning of the final application's components.

Product status link

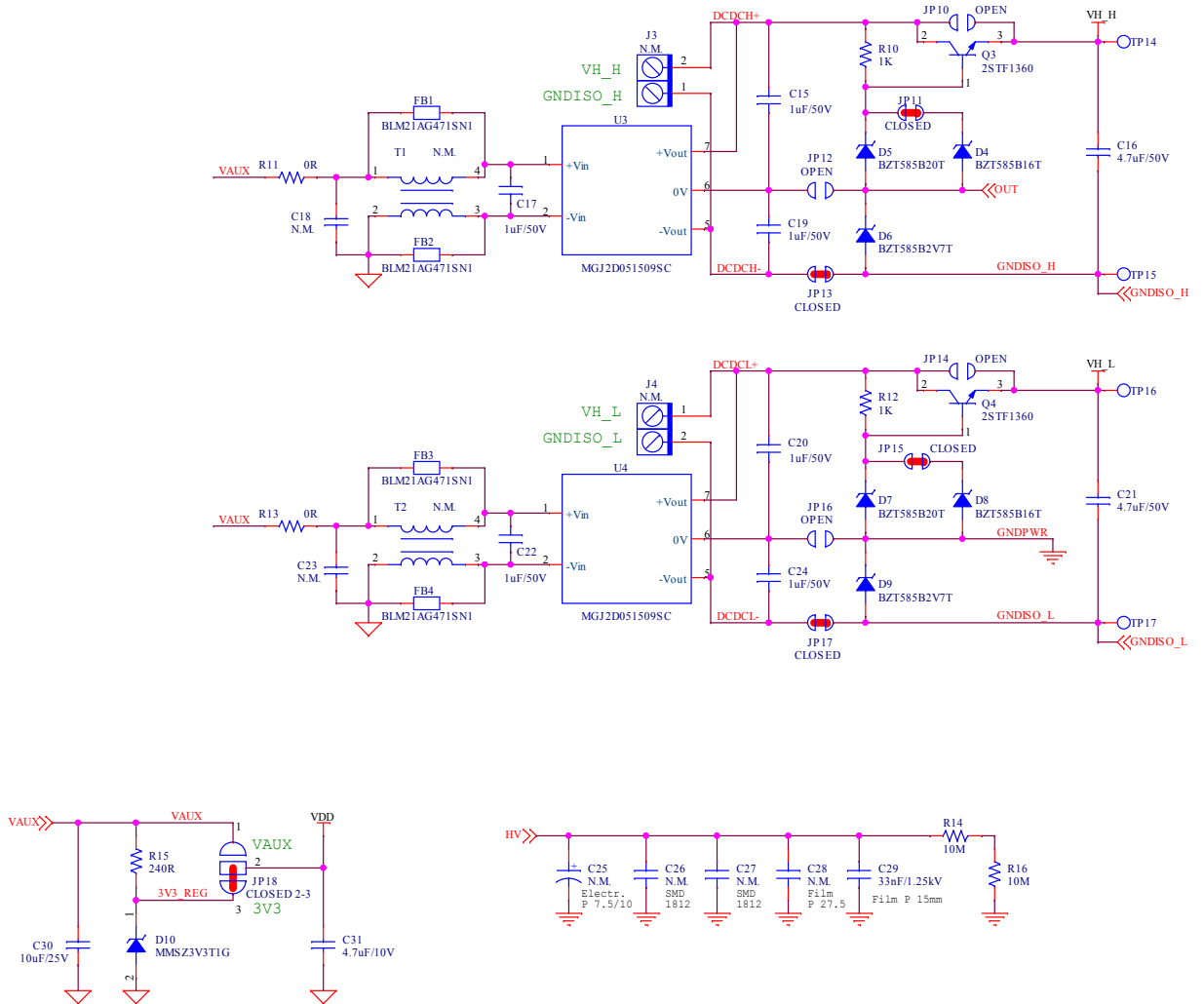
[EVALSTGAP2HSCM](#)

# 1 Schematic diagram

**Figure 1. EVALSTGAP2HSCM circuit schematic – gate drivers**



**Figure 2. EVALSTGAP2HSCM circuit schematic – supply, connectors and decoupling**



## 2 Bill of material

**Table 1. Bill of Material – components common to all device variants**

| Reference                                   | Description                                      | Value / Generic Part Number |
|---|--|-----------------------------|
| CN1,CN2,CN3                                 | Tab FASTON 250 horizontal                        | TE 928814-1                 |
| C1,C2,C8,C9                                 | SMT ceramic capacitor                            | 100 nF/50 V                 |
| C3,C7,C10,C14                               | SMT ceramic capacitor                            | 1 uF/50 V                   |
| C4,C11                                      | SMT ceramic capacitor                            | N.M.                        |
| C5,C6,C12,C13                               | SMT ceramic capacitor                            | 220 pF/25 V                 |
| C15,C17,C19,C20,C22,C24                     | SMT ceramic capacitor                            | 1 uF/50 V                   |
| C16,C21                                     | SMT ceramic capacitor                            | 4.7 uF/50 V                 |
| C18,C23                                     | SMT ceramic capacitor                            | N.M.                        |
| C25   | THT electrolytic capacitor                       | N.M.                        |
| C26,C27                                     | SMT ceramic capacitor                            | N.M.                        |
| C28   | Film capacitor                                   | N.M.                        |
| C29   | Film capacitor                                   | 33 nF/1.25k V               |
| C30   | SMT ceramic capacitor                            | 10 uF/25 V                  |
| C31   | SMT ceramic capacitor                            | 4.7 uF/10 V                 |
| D1,D3                                       | Automotive low drop power Schottky rectifier     | STPS2L40ZFY                 |
| D2  | High voltage ultrafast rectifier                 | STTH112A                    |
| D4,D8                                       | Surface mount precision Zener diode              | BZT585B16T                  |
| D5,D7                                       | Surface mount precision Zener diode              | BZT585B20T                  |
| D6,D9                                       | Surface mount precision Zener diode              | BZT585B2V7T                 |
| D10   | Zener Voltage Regulator 500 mW                   | MMSZ3V3T1G                  |
| FB1,FB2,FB3,FB4                             | Ferrite beads                                    | BLM21AG471SN1               |
| JP2,JP3,JP4,JP5,JP8,JP9,JP11,JP13,JP15,JP17 | SMT jumper                                       | Closed                      |
| JP1,JP6,JP7,JP10,JP12,JP14,JP16             | SMT jumper                                       | Open                        |
| JP18  | SMT jumper                                       | Closed 2-3                  |
| J1  | Connector terminal block T.H. 7 POS 3.5 mm       | MORSV-350-7P_screw          |
| J2  | Strip connector 7 POS, 2.54 mm                   | STRIP 1x7                   |
| J3,J4                                       | Connector terminal block T.H. 2 POS 5.08 mm      | N.M.                        |
| Q1,Q2                                       | N-channel IGBT or MOSFET up to 1700 V            | N.M.                        |
| Q1A,Q2A                                     | N-channel IGBT or MOSFET up to 1700 V            | N.M.                        |
| Q3,Q4                                       | Low voltage fast-switching NPN power transistors | 2STF1360                    |
| R1,R6                                       | SMT resistor                                     | 22R                         |
| R2,R8                                       | SMT resistor                                     | 2R2                         |
| R3,R4,R7,R9                                 | SMT resistor                                     | 100R                        |
| R5  | SMT resistor                                     | N.M.                        |
| R10,R12                                     | SMT resistor                                     | 1K                          |

| Reference   | Description                                     | Value / Generic Part Number |
|---|---|-----------------------------|
| R11,R13   | SMT resistor                                    | 0R                          |
| R14,R16   | SMT resistor                                    | 10M                         |
| R15   | SMT resistor                                    | 240R                        |
| TP1,TP2,TP3,TP4,TP5,TP6,TP7,TP8,<br>TP11,TP13,TP14,TP15,TP16,TP17 | Test point - PCB 1.5 mm diameter                | T POINT R                   |
| TP9,TP10,TP12   | THT ring test point                             | TPTH-ANELLO-1MM             |
| T1,T2   | Common mode choke, SMD 4.7x4.5 mm               | N.M.                        |
| U1,U2   | Galvanically isolated 4 A single gate driver    | STGAP2HSCM                  |
| U3,U4   | 5.2KVDC isolated 2W gate drive DC-DC converters | MGJ2D051509SC               |
| VP2   | PCB assembly version solder dot                 | Full                        |
| VP1,VP3,VP4   | PCB assembly version solder dot                 | Empty                       |
|   | P.C.B. EVALSTGAP2HS Rev.1                       |                             |

### 3 Layout and component placements

Figure 3. EVALSTGAP2HSCM – Layout (component placement top view)

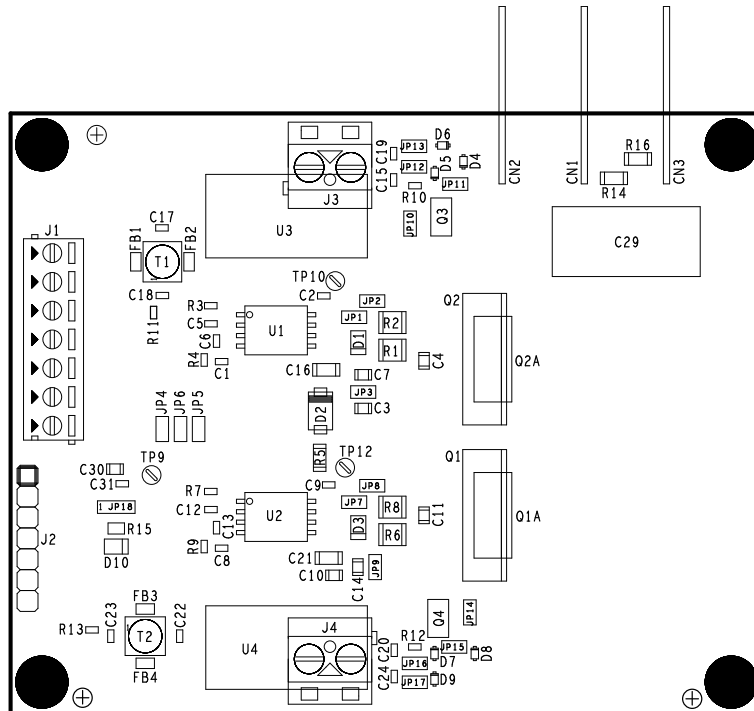
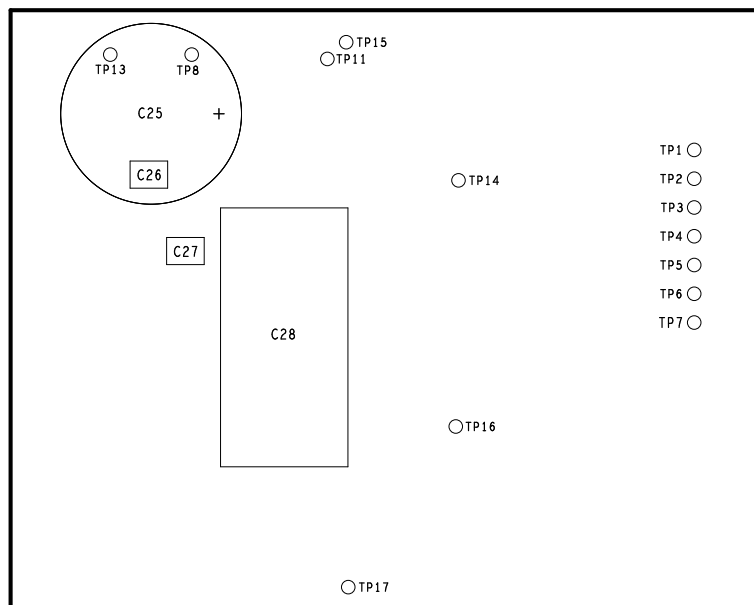
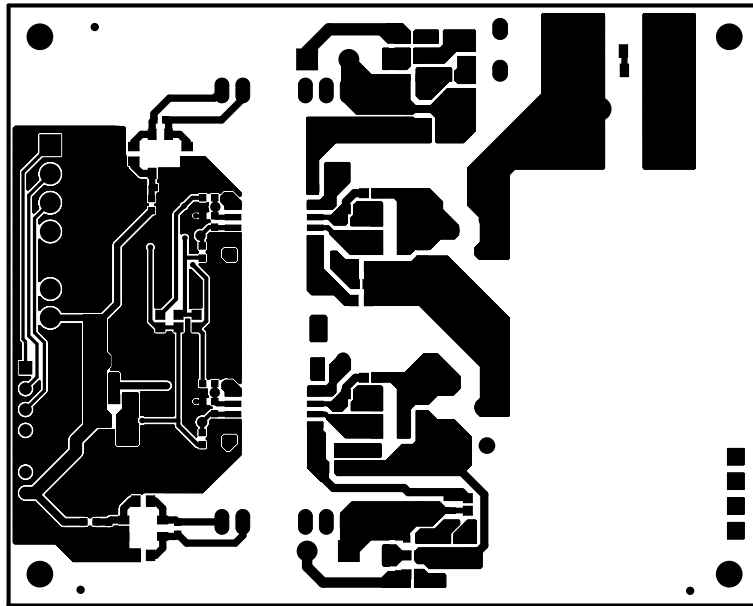


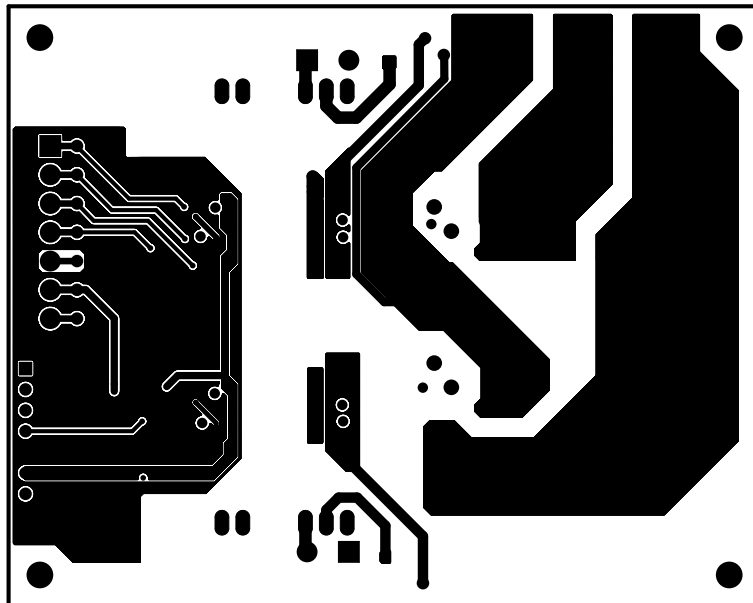
Figure 4. EVALSTGAP2HSCM – Layout (component placement bottom view)



**Figure 5. EVALSTGAP2HSCM – Layout (top layer)**



**Figure 6. EVALSTGAP2HSCM – Layout (bottom layer)**



## Revision history

**Table 2. Document revision history**

| Date        | Version | Changes          |
|-------------|---------|------------------|
| 08-Sep-2020 | 1       | Initial release. |



## Contents

|          |  |           |
|----------|--|-----------|
| <b>1</b> | <b>Schematic diagram</b> .....               | <b>2</b>  |
| <b>2</b> | <b>Bill of material</b> .....                | <b>4</b>  |
| <b>3</b> | <b>Layout and component placements</b> ..... | <b>6</b>  |
|          | <b>Revision history</b> .....                | <b>8</b>  |
|          | <b>Contents</b> .....                        | <b>9</b>  |
|          | <b>List of tables</b> .....                  | <b>10</b> |
|          | <b>List of figures</b> .....                 | <b>11</b> |

## List of tables

|                 |   |   |
|-----------------|---|---|
| <b>Table 1.</b> | Bill of Material – components common to all device variants . . . . . | 4 |
| <b>Table 2.</b> | Document revision history . . . . .                                   | 8 |

## List of figures

|                  |  |   |
|------------------|--|---|
| <b>Figure 1.</b> | EVALSTGAP2HSCM circuit schematic – gate drivers . . . . .                      | 2 |
| <b>Figure 2.</b> | EVALSTGAP2HSCM circuit schematic – supply, connectors and decoupling . . . . . | 3 |
| <b>Figure 3.</b> | EVALSTGAP2HSCM – Layout (component placement top view) . . . . .               | 6 |
| <b>Figure 4.</b> | EVALSTGAP2HSCM – Layout (component placement bottom view) . . . . .            | 6 |
| <b>Figure 5.</b> | EVALSTGAP2HSCM – Layout (top layer) . . . . .                                  | 7 |
| <b>Figure 6.</b> | EVALSTGAP2HSCM – Layout (bottom layer) . . . . .                               | 7 |

**IMPORTANT NOTICE – PLEASE READ CAREFULLY**

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, please refer to [www.st.com/trademarks](http://www.st.com/trademarks). All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2020 STMicroelectronics – All rights reserved

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components

*Click to view similar products for [Power Management IC Development Tools](#) category:*

*Click to view products by [STMicroelectronics](#) manufacturer:*

Other Similar products are found below :

[EVAL-ADM1168LQEBZ](#) [EVB-EP5348UI](#) [MIC23451-AAAYFL EV](#) [MIC5281YMME EV](#) [DA9063-EVAL](#) [ADP122-3.3-EVALZ](#) [ADP130-0.8-EVALZ](#) [ADP130-1.2-EVALZ](#) [ADP130-1.5-EVALZ](#) [ADP130-1.8-EVALZ](#) [ADP1714-3.3-EVALZ](#) [ADP1716-2.5-EVALZ](#) [ADP1740-1.5-EVALZ](#) [ADP1752-1.5-EVALZ](#) [ADP1828LC-EVALZ](#) [ADP1870-0.3-EVALZ](#) [ADP1871-0.6-EVALZ](#) [ADP1873-0.6-EVALZ](#) [ADP1874-0.3-EVALZ](#) [ADP1882-1.0-EVALZ](#) [ADP199CB-EVALZ](#) [ADP2102-1.25-EVALZ](#) [ADP2102-1.875EVALZ](#) [ADP2102-1.8-EVALZ](#) [ADP2102-2-EVALZ](#) [ADP2102-3-EVALZ](#) [ADP2102-4-EVALZ](#) [ADP2106-1.8-EVALZ](#) [ADP2147CB-110EVALZ](#) [AS3606-DB](#) [BQ24010EVM](#) [BQ24075TEVM](#) [BQ24155EVM](#) [BQ24157EVM-697](#) [BQ24160EVM-742](#) [BQ24296MEVM-655](#) [BQ25010EVM](#) [BQ3055EVM](#) [NCV891330PD50GEVB](#) [ISLUSBI2CKIT1Z](#) [LM2744EVAL](#) [LM2854EVAL](#) [LM3658SD-AEV/NOPB](#) [LM3658SDEV/NOPB](#) [LM3691TL-1.8EV/NOPB](#) [LM4510SDEV/NOPB](#) [LM5033SD-EVAL](#) [LP38512TS-1.8EV](#) [EVAL-ADM1186-1MBZ](#) [EVAL-ADM1186-2MBZ](#)